

Application Serial No. 10/517943  
Amendment and Response  
Office Action dated 10/05/2006

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### REMARKS

In the Specification, Applicants amended the title, the disclosure, and the summary, as requested. Applicants amended claims 1, 5-20 editorially. Applicants provided a proper antecedent basis for the "metal layers" in claims 10, 12, 13. Claims 1-20 are pending.

Applicants respectfully traverse the rejection of claim 1 under JP-A-2002-57009 (Keiji '009). Keiji '009 does not disclose or suggest a resistor having a plating layer extending continuously from one end of the resistor element to the other end of the resistor element. Applicants discuss the differences and the disadvantages set forth by Keiji '009 in the originally filed specification at page 3, line 17 through page 4, line 10 stating that the connection terminals attached to the lower surface of the resistor require melted solder that swells up beyond the connection terminals thereby changing the resistance. Applicants thus request the Examiner to withdraw the rejection of claim 1 as being anticipated under 35 U.S.C. §102(b).

The rejection of claims 1-20 under 35 U.S.C. §102(d) as being anticipated by Tsukada (JP2004-22658) is improper. The reference is a publication of Japanese application 2002-172892, one of the priority applications for the present application which is the U.S. national stage of international application no. PCT/JP03/07456 filed on 12 June 2003 and which was filed timely as the U.S. national stage on 24 December 2003. The Tsukada '658 reference (which appears to be only a published application and not a granted patent) was not "granted" prior to the PCT filing date of the present application, which is the effective U.S. filing date. Tsukada '658, therefore, is not prior art under 35 U.S.C. §102(d).

Applicants further traverse the rejection of claims 1-15 and 18-19 under 35 U.S.C. §102(b) as being anticipated by Kimura '274. Respectfully, Kimura '274 does not disclose or suggest a plating layer of pure metal extending continuously from one end of the resistor element to the other end, as in claim 1, or of forming a continuous plating layer on the upper surface of the resistor element as in claims 18 and 19. The arrangement of Kimura '274 wherein the top of the resistance layer 3 of Kimura '274 is

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covered with an insulating protective film layer 4 and the bottom is coated with an insulating substrate 1 and the electrodes and the solder are at the ends increases the thickness and the weight of the resistor, disadvantages postured by Applicants. The advantages of the pure metal plating, as in claims 1, 18, and 19, decreases the resistance between the electrodes without changing the ratio of the high resistance metal to the low resistance metal in the alloy of the resistor body and maintains the temperature coefficient of resistance without increasing the thickness and weight of the resistor, which are disadvantages of Kimura '274. Applicants maintain the patentability of claims 2-15 at least by virtue of their dependence upon claim 1. Applicants further respectfully request the Examiner to withdraw the rejection of claims 1-15 and 18-19.

Applicants do not admit the relevance of the Palanisamy '698 nor the Komeda 287 references to the pending claims. Applicants further request the Examiner to withdraw the rejections and pass the application to allowance.



Dated: February 5, 2007

Respectfully submitted,

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